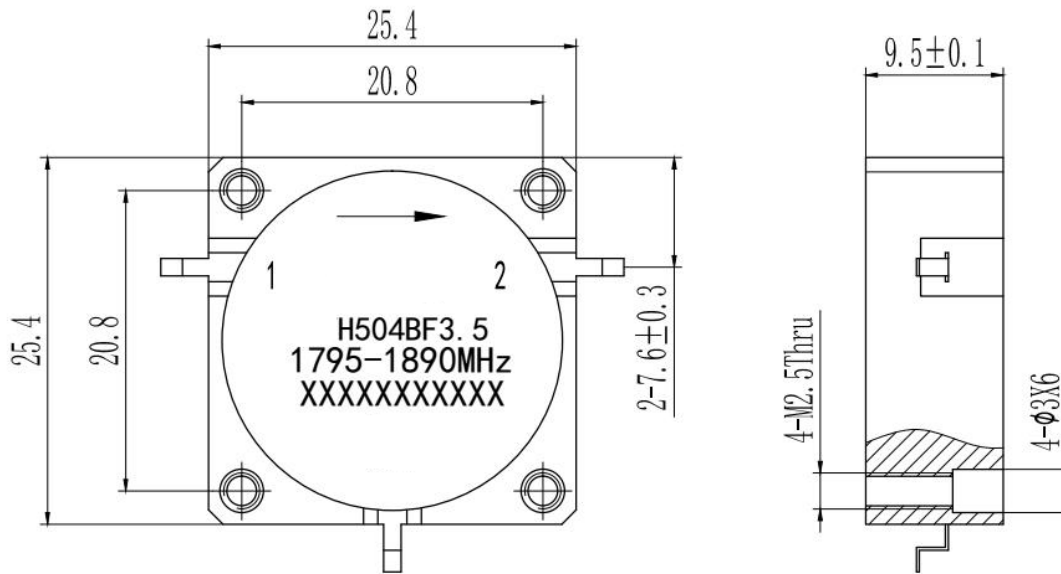


## 1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

## 2.Dimensions Unit:mm



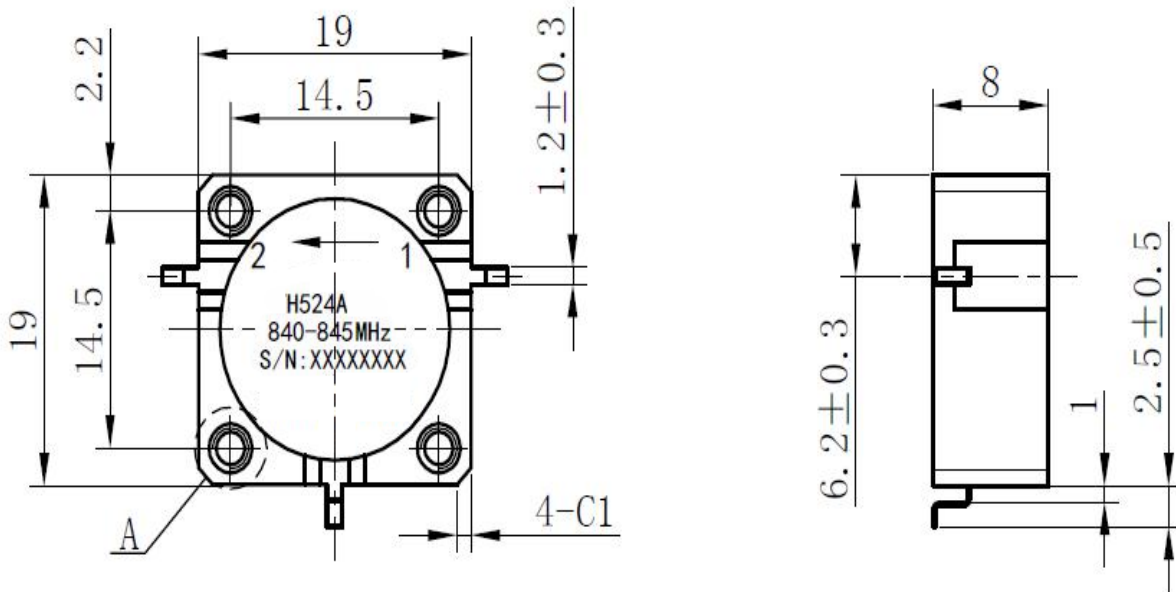
## 3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H504B3.5[850-900]MHz	0.850	0.900	0.8750	0.050	25	0.2	1.12	250	-70
H504B3.0[850-900]MHz	0.850	0.900	0.8750	0.050	25	0.2	1.12	250	-72
H504B3.0[925-960]MHz	0.925	0.960	0.9425	0.035	25	0.2	1.12	250	-75
H504B3.5[925-960]MHz	0.925	0.960	0.9425	0.035	25	0.2	1.12	250	-75
H504B3.0[1795-1890]MHz	1.795	1.890	1.8425	0.095	25	0.2	1.12	250	-75
H504B3.5[1795-1890]MHz	1.795	1.890	1.8425	0.095	25	0.2	1.12	250	-75
H504B3.0[2110-2170]MHz	2.110	2.170	2.1400	0.060	25	0.2	1.12	250	-75
H504B3.5[2110-2170]MHz	2.110	2.170	2.1400	0.060	25	0.2	1.12	250	-75

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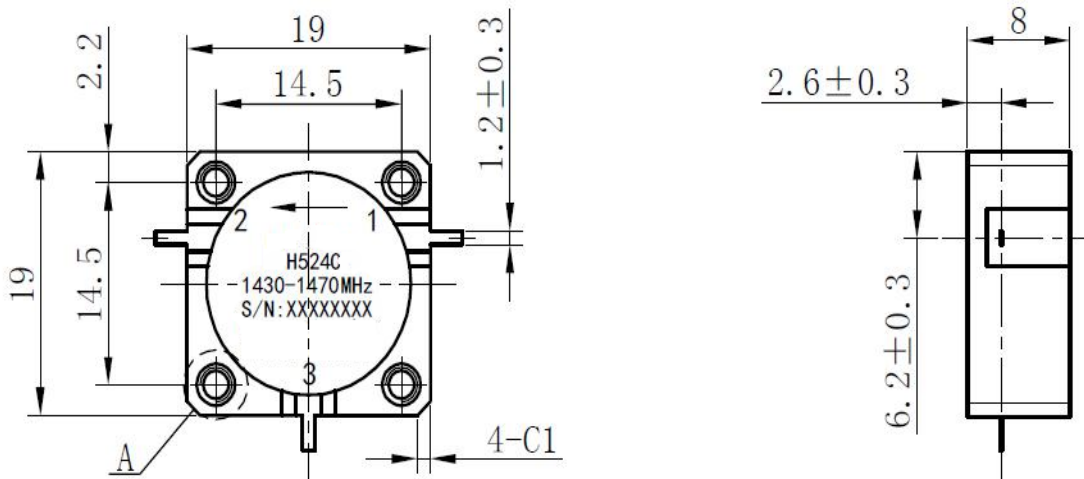
## 3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H524A [840-845]MHz	0.840	0.845	0.8425	0.005	20	0.35	1.2	100	
H524A [902-928]MHz	0.902	0.928	0.9150	0.026	22	0.3	1.17	100	
H524A [930-960]MHz	0.930	0.960	0.9450	0.030	22	0.3	1.17	100	
H524A [1805-2170]MHz	1.805	2.170	1.8875	0.165	22	0.3	1.17	150	-65
H524A [1900-3000]MHz	1.900	3.000	2.450	1.100	20	0.35	1.2	100	-60

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## 3.Specifications

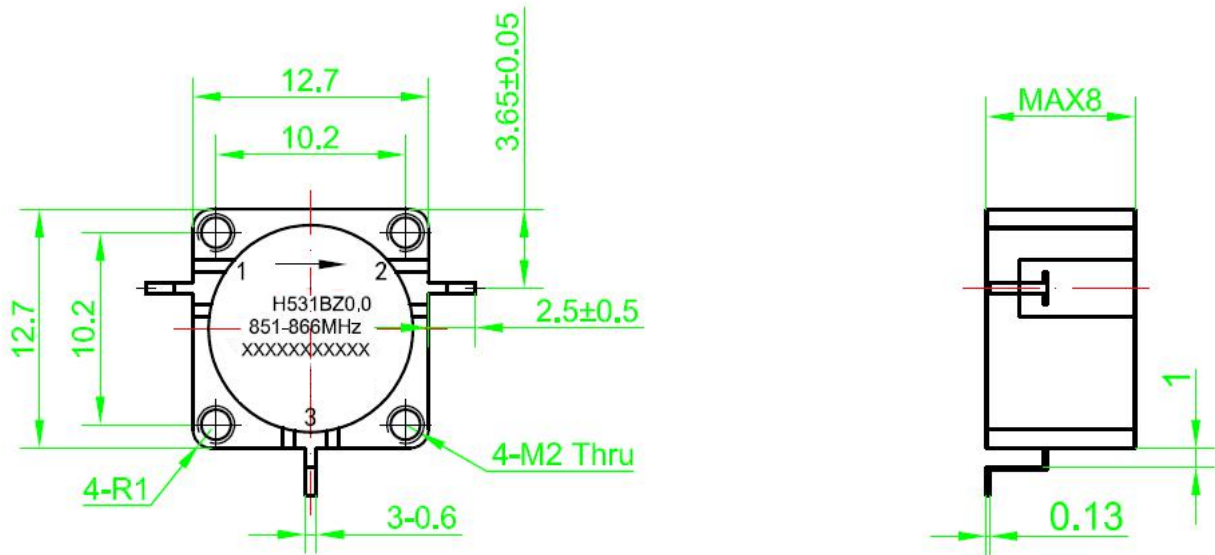
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H524C[1430-1470]MHz	1.430	1.470	1.4500	0.040	25	0.25	1.15	150	-70
H524C[1805-1920]MHz	1.805	1.920	1.8625	0.115	23	0.28	1.17	150	
H524C[1840-1920]MHz	1.840	1.920	1.8800	0.080	23	0.25	1.17	150	
H524C[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.17	150	
H524C[2300-2400]MHz	2.300	2.400	2.3500	0.100	23	0.25	1.17	150	
H524C[2300-2700]MHz	2.300	2.700	2.500	0.400	20	0.4	1.22	150	
H524C[2555-2655]MHz	2.555	2.655	2.605	0.100	23	0.25	1.17	100	
H524C[2500-2700]MHz	2.500	2.700	2.600	0.200	23	0.25	1.15	100	
H524C[3400-3800]MHz	3.400	3.800	3.600	0.400	23	0.25	2.3	100	
H524C[4100-4400]MHz	4.100	4.400	4.250	0.300	22	0.4	1.2	30	
H524C[4750-5100]MHz	4.750	5.100	4.925	0.350	22	0.35	1.2	10	



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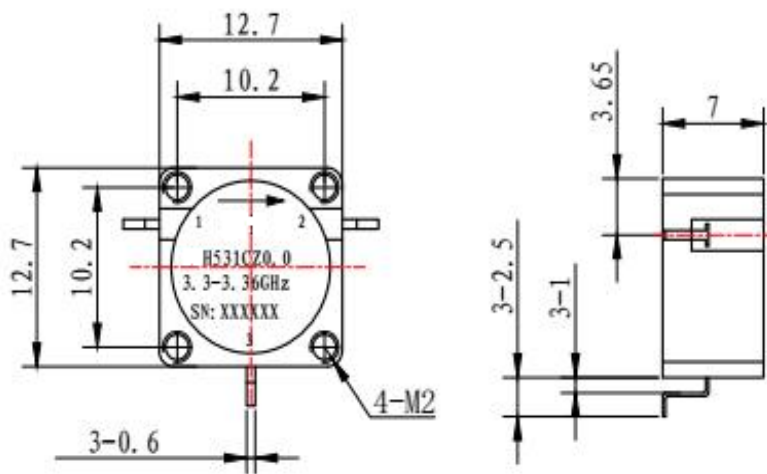
## 3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531B[851-866]MHz	0.851	0.866	0.8585	0.015	21	0.45	1.2	50	
H531B[865-880]MHz	0.865	0.880	0.8725	0.015	21	0.45	1.2	50	
H531B[930-960]MHz	0.930	0.960	0.9450	0.030	21	0.45	1.2	50	
H531B[1880-1920]MHz	1.880	1.920	1.900	0.040	23	0.3	1.15	100	
H531B[1805-2025]MHz	1.805	2.025	1.915	0.220	18	0.35	1.28	75	
H531B[1930-1995]MHz	1.930	1.995	1.963	0.065	23	0.3	1.15	100	
H531B[2110-2170]MHz	2.110	2.170	2.140	0.060	23	0.3	1.15	100	
H531B[2300-2400]MHz	2.300	2.400	2.350	0.100	23	0.3	1.15	100	
H531B[2400-2500]MHz	2.400	2.500	2.450	0.100	23	0.3	1.15	100	
H531B[2550-2650]MHz	2.550	2.650	2.600	0.100	23	0.3	1.15	100	

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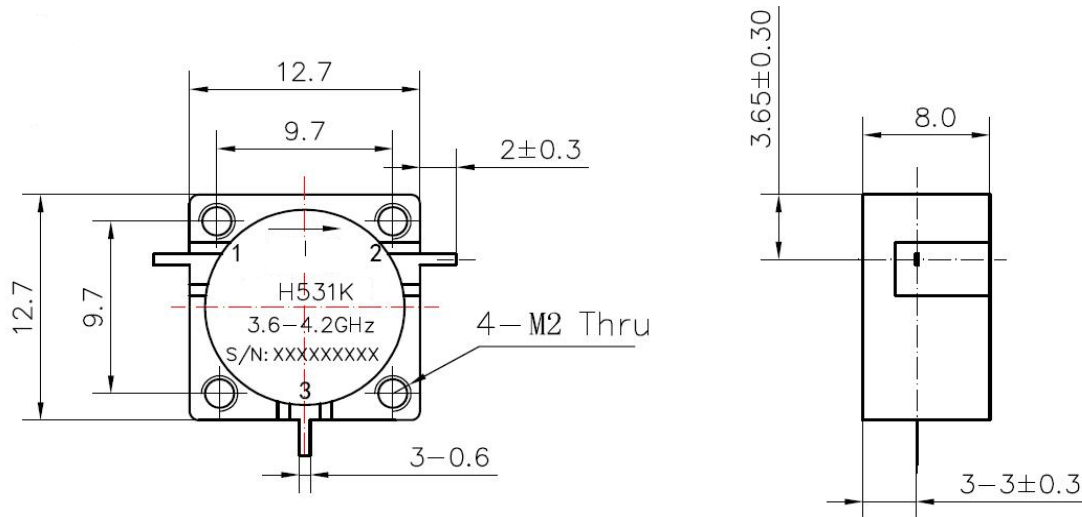
## 3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531C[3.3-3.36]MHz	3.300	3.360	3.3300	0.060	22	0.3	1.17	100	
H531C[3400-3700]MHz	3.400	3.700	3.5500	0.300	21	0.4	1.2	50	
H531C[5790-5890]MHz	5.790	5.890	5.8500	0.100	23	0.3	1.17	20	

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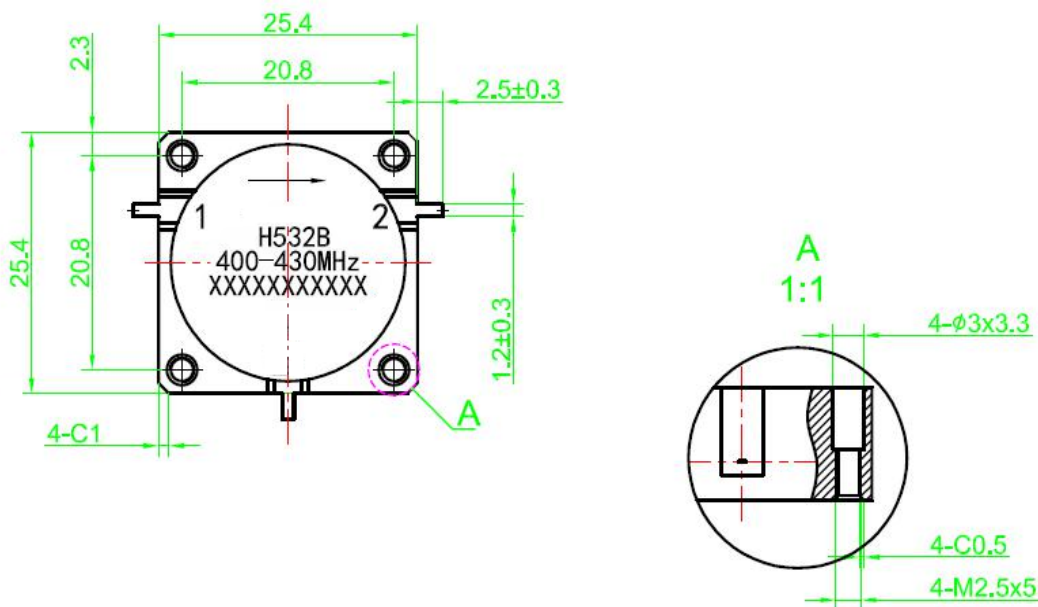
## 3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531K[3.6-4.2]GHz	3.600	4.200	3.9000	0.600	20	0.35	1.25	50	
H531K[3.7-4.13]GHz	3.700	4.130	3.9150	0.430	20	0.35	1.25	50	
H531K[4.4-5]GHz	4.400	5.000	4.7000	0.600	20	0.35	1.25	50	
H531K[5.15-5.9]GHz	5.150	5.900	5.5250	0.750	20	0.35	1.25	50	
H531K[7.1-7.5]GHz	7.100	7.500	7.300	0.400	22	0.4	1.2	10	
H531K[9.2-9.8]GHz	9.200	9.800	9.500	0.600	21	0.4	1.2	60	
H531K[10.1-10.6]GHz	10.100	10.600	10.350	0.500	22	0.4	1.2	20	

## 1.Features

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## 3.Specifications

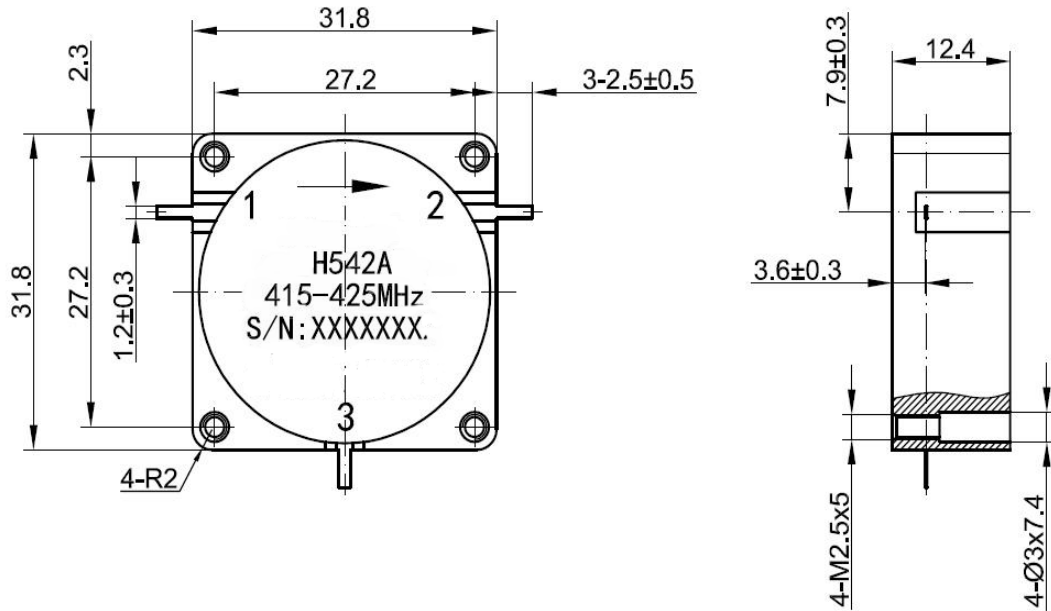
Part No.	Frequency (GHz)		Center Frequency (GHz)	Bandwidth (GHz)	Isolation (dB) MIN	INS LOSS (dB) MAX	VSWR (dB) MAX	Power (W)	IMD (@2X43dBm) (-dBc) MAX
	F1	F2							
H532B [400-430]MHz	0.400	0.430	0.4150	0.030	20	0.4	1.22	200	
H532B [566-600] MHz	0.566	0.600	0.5830	0.034	23	0.25	1.15	200	
H532B [566-678]MHz	0.566	0.678	0.6215	0.112	18	0.45	1.28	200	
H532B [600-684]MHz	0.600	0.684	0.6420	0.084	20	0.35	1.2	100	
H532B [600-700]MHz	0.600	0.700	0.6500	0.100	23	0.35	1.15	200	-65
H532B [700-740]MHz	0.700	0.740	0.7200	0.040	22	0.22	0.25	100	-70
H532B [758-803]MHz	0.758	0.803	0.7805	0.045	25	0.2	1.12	250	-70
H532B [925-960]MHz	0.925	0.960	0.9425	0.035	25	0.2	1.12	250	-75
H532B [1805-1880]MHz	1.805	1.880	1.838	0.075	23	0.25	1.15	300	-75
H532B [1930-1995]MHz	1.930	1.995	1.963	0.075	23	0.25	1.15	300	-75
H532B [2110-2170]MHz	2.110	2.170	2.140	0.060	25	0.2	1.12	250	-75



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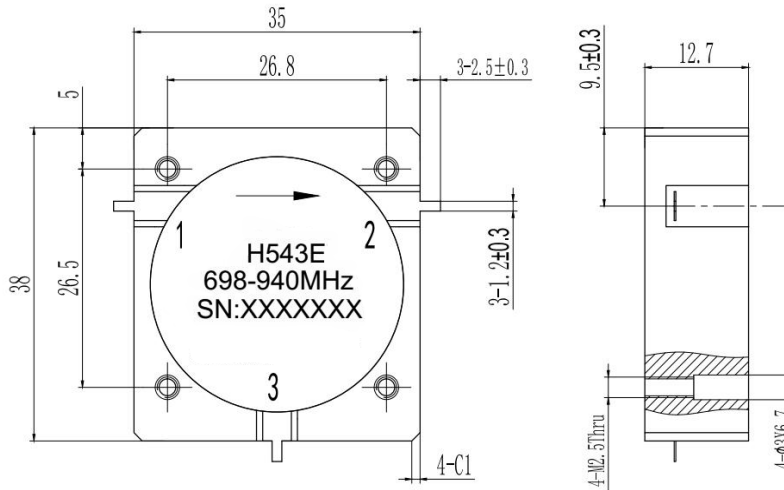
## 3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H542A [415-425]MHz	0.415	0.425	0.4200	0.010	22	0.35	1.17	100	
H542A [470-510]MHz	0.470	0.510	0.4850	0.040	20	0.15	1.22	100	
H542A [560-680]MHz	0.560	0.680	0.6200	0.080	20	0.15	1.22	100	
H542A [700-960]MHz	0.700	0.960	0.8300	0.260	16	0.5	1.38	300	
H542A [925-960]MHz	0.925	0.960	0.9425	0.035	25	0.25	1.12	400	-75
H542A [1217-1238]MHz	1.217	1.238	1.2275	0.021	23	0.25	1.15	300	
H542A [1565-1586]MHz	1.565	1.586	1.5755	0.021	23	0.25	1.15	300	
H542A [1710-1785]MHz	1.710	1.785	1.7475	0.075	23	0.25	1.15	400	-70
H542A [1800-2175]MHz	1.800	2.175	1.9875	0.375	22	0.3	1.17	300	
H542A [1805-1880]MHz	1.805	1.880	1.838	0.075	25	0.2	1.12	350	-75
H542A [2110-2170]MHz	2.110	2.170	2.140	0.060	23	0.25	1.15	400	-75

## 1.Features

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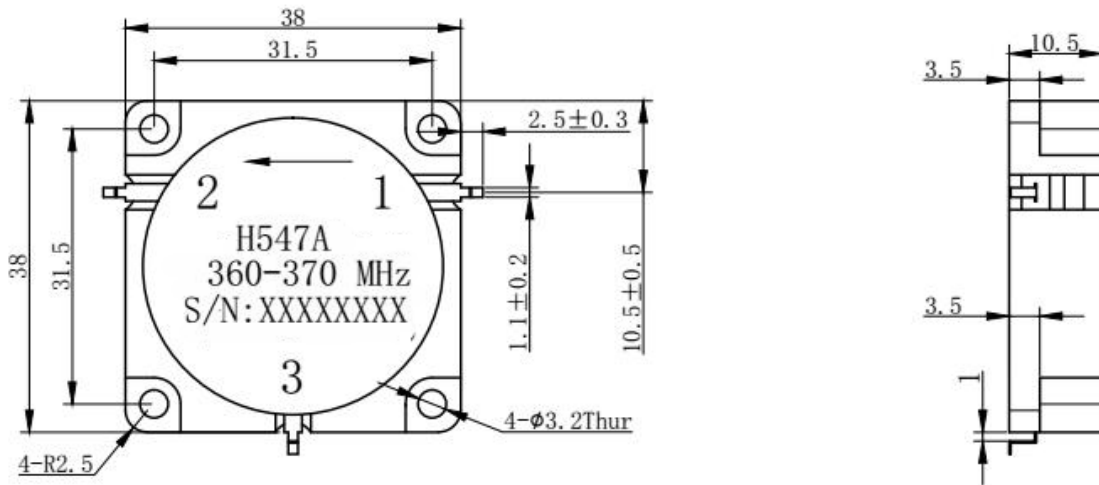
## 3.Specifications

Part No.	Frequency (GHz)		Center Frequnc	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H543E [330-350]MHz	0.330	0.350	0.340	0.020	20	0.45	1.22	100	
H543E [400-430]MHz	0.400	0.430	0.4250	0.030	22	0.25	1.17	200	
H543E [470-570]MHz	0.470	0.570	0.5200	0.100	20	0.4	1.2	200	
H543E [500-650]MHz	0.500	0.650	0.5750	0.150	18	0.45	1.28	100	
H543E [698-940]MHz	0.698	0.940	0.8190	0.242	18	0.4	1.28	100	

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## 3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H547A0.0[360-370]MHz	0.360	0.370	0.365	0.010	23	0.25	1.15	150	
H547A0.0[395-435]MHz	0.385	0.435	0.4050	0.040	19	0.45	1.25	150	-60
H547A0.0[415-425]MHz	0.415	0.425	0.4200	0.010	22	0.35	1.17	200	
H547A0.0[470-520]MHz	0.470	0.520	0.4950	0.050	20	0.35	1.22	200	
H547A0.0[566-678]MHz	0.566	0.678	0.6220	0.112	20	0.45	1.22	150	-65

# Drop-in Circulator

## Features:

- UMTS, LTE Band
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## ELECTRICAL CHARACTERISTICS:

Model	Freq (GHz)	Bandwidth (MHz,max.)	Insertion Loss (dB,max.)	Isolation (dB,min.)	VSWR (dB,min.)	Average Power (W,max)	Temperature ( °C )	Dimensions (mm)
H6060H	0.02-0.4	175	2	18	1.3	100	-10 - +60	60*60*25.5
H6466H	0.02-0.4	175	2	18	1.3	100	-10 - +60	64*66*22
H5050X	0.15-0.33	70	0.7	18	1.3	400	-30 - +70	50.8*50.8*14.8
H4545X	0.3-1	300	0.5	18	1.3	400	-30 - +70	45*45*13
H3538X	0.3-1.85	500	0.7	18	1.35	300	-30 - +70	35*35*11
H3838X	0.3-1.85	106	0.4	20	1.25	300	-30 - +70	38*38*11
H2525X	0.35-4	770	0.65	15	1.45	250	-30 - +70	25.4*25.4*10
H2020X	0.6-4	900	0.5	18	1.35	100	-30 - +70	20*20*8.6
H1919X	0.8-4.3	900	0.5	18	1.35	100	-30 - +70	19*19*8.6
H6466K	0.95-2	1050	0.7	16	1.4	100	-10 - +60	64*66*26
H1313T	1.71-5.9	800	0.45	18	1.3	100	-30 - +70	12.7*12.7*7.2
H5050A	1.5-3	1500	0.7	17	1.4	100	0 - +60	50.8*49.5*19
H4040A	1.7-3	1200	0.7	16	1.35	200	0 - +60	40*40*20
H1313M	1.71-5.9	800	0.45	18	1.3	100	-30 - +70	12.7*12.7*7.2
H2528C	2.7-6	3500	0.8	16	1.4	200	-30 - +70	25.4*28*14
H3234A	2-4	2000	0.6	16	1.35	100	0 - +60	32*34*21
H1822D	4-5	1000	0.4	18	1.35	60	-30 - +70	18*22*10.4
H2123B	4-8	4000	0.6	18	1.35	60	0 - +60	21*22.5*15
H1220D	5-6.5	800	0.5	18	1.3	60	-30 - +70	12*20*9.5
H1623D	5-6.5	800	0.5	18	1.3	50	-30 - +70	16*23*9.7
H1319C	6-12	4000	0.5	18	1.3	50	0 - +60	13*19*12.7
H0915D	7-18	6000	0.6	17	1.35	30	-30 - +70	8.9*15*7.8